

# High Temperature 150°C, X8L Dielectric, 10 – 50 VDC (Commercial & Automotive Grade)

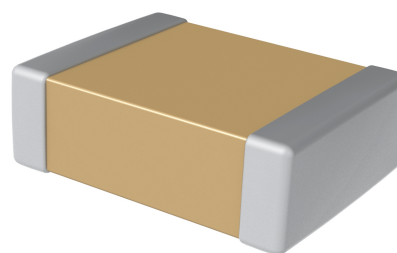
## Overview

KEMET's X8L dielectric features a 150°C maximum operating temperature and is considered "general purpose high temperature." These components are fixed, ceramic dielectric capacitors suited for high temperature bypass and decoupling applications or frequency discriminating circuits where Q and stability of capacitance characteristics are not critical. X8L exhibits a predictable change in capacitance with respect to time and voltage and boasts a minimal change in capacitance with reference to ambient temperature up to 125°C. Beyond 125°C X8L displays a wider variation in capacitance. Capacitance change is limited to  $\pm 15\%$  from -55°C to +125°C and +15, -40% from 125°C to 150°C.

Driven by the demand for a more robust and reliable component, X8L dielectric capacitors were developed for critical applications where reliability at higher operating temperatures are a concern. These capacitors are widely used in automotive circuits as well as general high temperature applications. Concerned with flex cracks resulting from excessive tensile and shear stresses produced during board flexure and thermal cycling? These devices are available with KEMET's Flexible termination technology which inhibits the transfer of board stress to the rigid ceramic body, therefore mitigating flex cracks

which can result in low IR or short circuit failures. Although flexible termination technology does not eliminate the potential for mechanical damage that may propagate during extreme environmental and handling conditions, it does provide superior flex performance over standard termination systems.

In addition to commercial grade, automotive grade devices are available and meet the demanding Automotive Electronics Council's AEC-Q200 qualification requirements.



## Ordering Information

C	1210	X	106	K	8	N	A	C	TU
Ceramic	Case Size (L" x W")	Specification/ Series <sup>1</sup>	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Dielectric	Failure Rate/ Design	Termination Finish <sup>2</sup>	Packaging/Grade (C-Spec) <sup>3</sup>
	0402 0603 0805 1206 1210	C = Standard X = Flexible Termination	2 significant digits + number of zeros	J = $\pm 5\%$ K = $\pm 10\%$ M = $\pm 20\%$	8 = 10 V 3 = 25 V 5 = 50 V	N = X8L	A = N/A	C = 100% Matte Sn L = SnPb (5% minimum)	See "Packaging C-Spec Ordering Options Table" below

<sup>1</sup> The flexible termination option is not available on EIA 0402 case size product. "C" must be used in the 6th character position when ordering this case size.

<sup>2</sup> Additional termination finish options may be available. Contact KEMET for details.

<sup>2,3</sup> SnPb termination finish option is not available on Automotive Grade product.

<sup>3</sup> Additional reeling or packaging options may be available. Contact KEMET for details.

## Packaging C-Spec Ordering Options Table

Packaging Type	Packaging/Grade Ordering Code (C-Spec)
<b>Commercial Grade<sup>1</sup></b>	
Bulk Bag	Blank
7" Tape & Reel/Unmarked	TU
7" Tape & Reel/Marked	TM
<b>Automotive Grade<sup>2</sup></b>	
7" Reel	AUTO
13" Reel/Punched Paper	AUTO 7411
13" Reel/Embossed Plastic	AUTO 7210

<sup>1</sup> C-Spec not required when ordering "Bulk Bag" packaging option.

<sup>1</sup> The terms "Marked" and "Unmarked" pertain to laser marking option of components.

<sup>2</sup> Reeling tape options (Paper or Plastic) are dependent on capacitor case size (L"x W") and thickness dimension. See "Chip Thickness/Packaging Quantities" and "Tape & Reel Packaging Information" sections of this document.

<sup>2</sup> For additional Information regarding "AUTO" C-Spec options, see "Automotive C-Spec Information" section of this document.

<sup>2</sup> All Automotive packaging C-Specs listed exclude packaging of laser mark components. Please contact KEMET if you require a laser marked option.

## Benefits

- -55°C to +150°C operating temperature range
- Lead (Pb)-Free, RoHS and REACH compliant
- EIA 0402, 0603, 0805, 1206, and 1210 case sizes
- DC voltage ratings of 10 V, 25 V, and 50 V
- Capacitance offerings ranging from 0.012 µF to 10 µF
- Available capacitance tolerances of ±5%, ±10%, and ±20%
- Commercial & Automotive (AEC-Q200) grades available
- Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish allowing for excellent solderability
- SnPb termination finish option available upon request (5% minimum)
- Flexible termination option available upon request

## Applications

Typical applications include use in extreme environments such as down-hole oil exploration, under-hood automotive, military and aerospace.

## Automotive C-Spec Information

KEMET Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. These products are supported by a Product Change Notification (PCN) and Production Part Approval Process warrant (PPAP).

Automotive products offered through our distribution channel have been assigned an inclusive ordering code C-Spec, "AUTO". This C-Spec was developed in order to better serve small and medium sized companies that prefer an automotive grade component without the requirement to submit a customer Source Controlled Drawing (SCD) or specification for review by a KEMET engineering specialist. This C-Spec is therefore not intended for use by KEMET's OEM Automotive customers and are not granted the same "privileges" as other automotive C-Specs. Customer PCN approval and PPAP request levels are limited (see details below).

### Product Change Notification (PCN)

The KEMET Product Change Notification system is used to communicate primarily the following types of changes:

- Product/process changes that affect product form, fit, function, and /or reliability
- Changes in manufacturing site
- Product obsolescence

KEMET Automotive C-Spec	Customer Notification due to:		Days prior to implementation
	Process/Product change	Obsolescence*	
KEMET assigned <sup>1</sup>	Yes (with approval and sign off)	Yes	180 days Minimum
AUTO	Yes (without approval)	Yes	90 days Minimum

<sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

### Production Part Approval Process (PPAP)

The purpose of the Production Part Approval Process is:

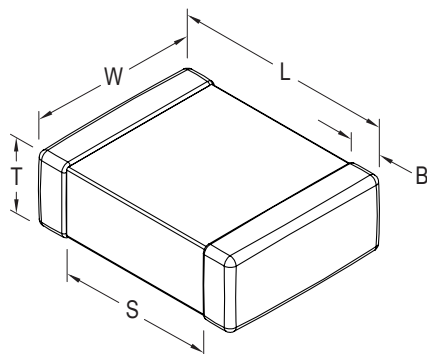
- To ensure that supplier can meet the manufacturability and quality requirements for the purchased parts.
- To provide the evidence that all customer engineering design record and specification requirements are properly understood and fulfilled by the manufacturing organization.
- To demonstrate that the established manufacturing process has the potential to produce the part

KEMET Automotive C-Spec	PPAP (Product Part Approval Process) Level				
	1	2	3	4	5
KEMET assigned <sup>1</sup>	•	•	•	•	•
AUTO	○		○		

<sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

- Part Number specific PPAP available
- Product family PPAP only

## Dimensions – Standard Termination – Millimeters (Inches)



EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Minimum	Mounting Technique
0402	1005	1.00 (0.040) ±0.05 (0.002)	0.50 (0.020) ±0.05 (0.002)	See Table 2 for Thickness	0.30 (0.012) ±0.10 (0.004)	0.30 (0.012)	Solder Reflow Only
0603	1608	1.60 (0.063) ±0.15 (0.006)	0.80 (0.032) ±0.15 (0.006)		0.35 (0.014) ±0.15 (0.006)	0.70 (0.028)	Solder Wave or Solder Reflow
0805	2012	2.00 (0.079) ±0.20 (0.008)	1.25 (0.049) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)	0.75 (0.030)	
1206	3216	3.20 (0.126) ±0.20 (0.008)	1.60 (0.063) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)	N/A	Solder Reflow Only
1210	3225	3.20 (0.126) ±0.20 (0.008)	2.50 (0.098) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)		

## Dimensions – Flexible Termination – Millimeters (Inches)

EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Minimum	Mounting Technique
0603	1608	1.60 (0.064) ±0.17 (0.007)	0.80 (0.032) ±0.15 (0.006)	See Table 2 for Thickness	0.45 (0.018) ±0.15 (0.006)	0.58 (0.023)	Solder Wave or Solder Reflow
0805	2012	2.00 (0.079) ±0.20 (0.008)	1.25 (0.049) ±0.20 (0.008)		0.50 (0.02) ±0.25 (0.010)	0.75 (0.030)	
1206	3216	3.30 (0.130) ±0.40 (0.016)	1.60 (0.063) ±0.20 (0.008)		0.60 (0.024) ±0.25 (0.010)	N/A	
1210	3225	3.30 (0.130) ±0.40 (0.016)	2.50 (0.098) ±0.20 (0.008)		0.60 (0.024) ±0.25 (0.010)		Solder Reflow Only

## Qualification/Certification

Commercial Grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance & Reliability.

Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC-Q200, please visit their website at [www.aecouncil.com](http://www.aecouncil.com).

## Environmental Compliance

Lead (Pb)-Free, RoHS, and REACH compliant without exemptions (excluding SnPb termination finish option).



RoHS Compliant

## Electrical Parameters/Characteristics

Item	Parameters/Characteristics
Operating Temperature Range	-55°C to +150°C
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	±15% (-55°C – 125°C) +15, -40% (125°C – 150°C)
Aging Rate (Maximum % Capacitance Loss/Decade Hour)	3.0%
Dielectric Withstanding Voltage (DWV)	250% of rated voltage (5 ±1 seconds and charge/discharge not exceeding 50 mA)
Dissipation Factor (DF) Maximum Limit @ 25°C	3.5% (10 V) and 2.5% (25 V and 50 V)
Insulation Resistance (IR) Limit @ 25°C	500 megohm microfarads or 10 GΩ (Rated voltage applied for 120 ±5 seconds @ 25°C)

Regarding aging rate: Capacitance measurements (including tolerance) are indexed to a referee time of 1,000 hours.

To obtain IR limit, divide MΩ-μF value by the capacitance and compare to GΩ limit. Select the lower of the two limits.

Capacitance and dissipation factor (DF) measured under the following conditions:

1 kHz ±50 Hz and 1.0 ±0.2 Vrms.

Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 and Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON."

## Post Environmental Limits

High Temperature Life, Biased Humidity, Moisture Resistance					
Dielectric	Rated DC Voltage	Capacitance Value	Dissipation Factor (Maximum %)	Capacitance Shift	Insulation Resistance
X8L	> 25	All	3.0	±20%	10% of Initial Limit
	25		5.0		
	10		7.5		

## Insulation Resistance Limit Table (X8L Dielectric)

EIA Case Size	1,000 Megohm Microfarads or 100 GΩ	500 Megohm Microfarads or 10 GΩ
0201	N/A	ALL
0402	< .012 $\mu$ F	$\geq$ .012 $\mu$ F
0603	< .047 $\mu$ F	$\geq$ .047 $\mu$ F
0805	< 0.15 $\mu$ F	$\geq$ 0.15 $\mu$ F
1206	< 0.47 $\mu$ F	$\geq$ 0.47 $\mu$ F
1210	< 0.39 $\mu$ F	$\geq$ 0.39 $\mu$ F
1808	ALL	N/A
1812	< 2.2 $\mu$ F	$\geq$ 2.2 $\mu$ F
1825	ALL	N/A
2220	< 10 $\mu$ F	$\geq$ 10 $\mu$ F
2225	ALL	N/A

**Table 1 – Capacitance Range/Selection Waterfall (0402 – 1210 Case Sizes)**

Capacitance	Cap Code	Case Size/ Series			C0402C		C0603C			C0805C			C1206C			C1210C		
		Voltage Code			8	3	8	3	5	8	3	5	8	3	5	8	3	5
		Rated Voltage (VDC)			10	25	10	25	50	10	25	50	10	25	50	10	25	50
		Capacitance Tolerance			Product Availability and Chip Thickness Codes See Table 2 for Chip Thickness Dimensions													
12,000 pF	123	J	K	M	BB	BB												
15,000 pF	153	J	K	M	BB	BB												
18,000 pF	183	J	K	M	BB	BB												
22,000 pF	223	J	K	M	BB	BB												
27,000 pF	273	J	K	M	BB	BB												
33,000 pF	333	J	K	M	BB													
39,000 pF	393	J	K	M	BB													
47,000 pF	473	J	K	M	BB		CF	CF	CF									
56,000 pF	563	J	K	M														
68,000 pF	683	J	K	M														
82,000 pF	823	J	K	M														
0.10 µF	104	J	K	M			CF	CF										
0.12 µF	124	J	K	M			CF	CF										
0.15 µF	154	J	K	M			CF	CF		DG	DG	DG						
0.18 µF	184	J	K	M			CF			DG	DG	DG						
0.22 µF	224	J	K	M			CF			DD	DD	DD						
0.27 µF	274	J	K	M						DD	DD	DD						
0.33 µF	334	J	K	M						DD	DD	DD						
0.39 µF	394	J	K	M						DE	DE	DE				FD	FD	FD
0.47 µF	474	J	K	M						DE	DE	DE	EG	EG	EG	FD	FD	FD
0.56 µF	564	J	K	M						DG	DH					FF	FF	FF
0.68 µF	684	J	K	M						DG	DH					FG	FG	FG
0.82 µF	824	J	K	M						DG						FL	FL	FL
1.0 µF	105	J	K	M						DG			ED	ED		FM	FM	FM
1.2 µF	125	J	K	M						DG			EH	EH		FG	FG	
1.5 µF	155	J	K	M									EH	EH		FG	FG	
1.8 µF	185	J	K	M									EF	EH		FG	FG	
2.2 µF	225	J	K	M									EF	EH		FG	FG	
2.7 µF	275	J	K	M									EH			FG	FH	
3.3 µF	335	J	K	M									EH			FM	FM	
3.9 µF	395	J	K	M									EH			FG	FK	
4.7 µF	475	J	K	M									EH			FG	FS	
5.6 µF	565	J	K	M												FH		
6.8 µF	685	J	K	M												FM		
8.2 µF	825	J	K	M												FK		
10 µF	106	J	K	M												FS		
Capacitance	Cap Code	Rated Voltage (VDC)			10	25	10	25	50	10	25	50	10	25	50	10	25	50
		Voltage Code			8	3	8	3	5	8	3	5	8	3	5	8	3	5
		Case Size/ Series			C0402C		C0603C			C0805C			C1206C			C1210C		

**Table 2 – Chip Thickness/Packaging Quantities**

Thickness Code	Case Size	Thickness ± Range (mm)	Paper Quantity		Plastic Quantity	
			7" Reel	13" Reel	7" Reel	13" Reel
BB	0402	0.50 ± 0.05	10,000	50,000	0	0
CF	0603	0.80 ± 0.07*	4,000	15,000	0	0
DP	0805	0.90 ± 0.10*	4,000	15,000	0	0
DE	0805	1.00 ± 0.10	0	0	2,500	10,000
DG	0805	1.25 ± 0.15	0	0	2,500	10,000
DH	0805	1.25 ± 0.20	0	0	2,500	10,000
ED	1206	1.00 ± 0.10	0	0	2,500	10,000
EF	1206	1.20 ± 0.15	0	0	2,500	10,000
EG	1206	1.60 ± 0.15	0	0	2,000	8,000
EH	1206	1.60 ± 0.20	0	0	2,000	8,000
FD	1210	0.95 ± 0.10	0	0	4,000	10,000
FF	1210	1.10 ± 0.10	0	0	2,500	10,000
FG	1210	1.25 ± 0.15	0	0	2,500	10,000
FL	1210	1.40 ± 0.15	0	0	2,000	8,000
FH	1210	1.55 ± 0.15	0	0	2,000	8,000
FM	1210	1.70 ± 0.20	0	0	2,000	8,000
FK	1210	2.10 ± 0.20	0	0	2,000	8,000
FS	1210	2.50 ± 0.30	0	0	1,000	4,000
Thickness Code	Case Size	Thickness ± Range (mm)	7" Reel	13" Reel	7" Reel	13" Reel
			Paper Quantity		Plastic Quantity	

Package quantity based on finished chip thickness specifications.



**Table 3A – Land Pattern Design Recommendations per IPC–7351 – Standard Termination**

EIA Size Code	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)					Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)				
		C	Y	X	V1	V2	C	Y	X	V1	V2	C	Y	X	V1	V2
0402	1005	0.50	0.72	0.72	2.20	1.20	0.45	0.62	0.62	1.90	1.00	0.40	0.52	0.52	1.60	0.80
0603	1608	0.90	1.15	1.10	4.00	2.10	0.80	0.95	1.00	3.10	1.50	0.60	0.75	0.90	2.40	1.20
0805	2012	1.00	1.35	1.55	4.40	2.60	0.90	1.15	1.45	3.50	2.00	0.75	0.95	1.35	2.80	1.70
1206	3216	1.60	1.35	1.90	5.60	2.90	1.50	1.15	1.80	4.70	2.30	1.40	0.95	1.70	4.00	2.00
1210	3225	1.60	1.35	2.80	5.65	3.80	1.50	1.15	2.70	4.70	3.20	1.40	0.95	2.60	4.00	2.90
1210 <sup>1</sup>	3225	1.50	1.60	2.90	5.60	3.90	1.40	1.40	2.80	4.70	3.30	1.30	1.20	2.70	4.00	3.00

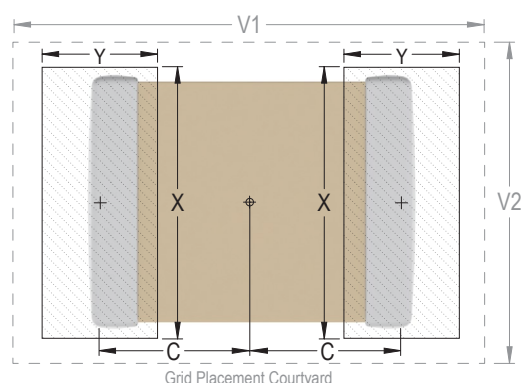
<sup>1</sup> Only for capacitance values  $\geq 22 \mu\text{F}$

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805 and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

**Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC–7351).

Image below based on Density Level B for an EIA 1210 case size.



**Table 3B – Land Pattern Design Recommendations per IPC–7351 – Flexible Termination**

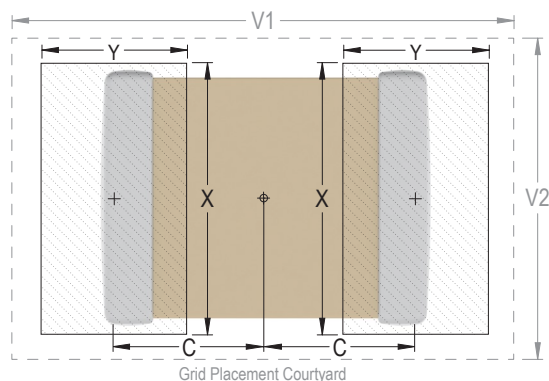
EIA Size Code	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)					Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)				
		C	Y	X	V1	V2	C	Y	X	V1	V2	C	Y	X	V1	V2
0603	1608	0.85	1.25	1.10	4.00	2.10	0.75	1.05	1.00	3.10	1.50	0.65	0.85	0.90	2.40	1.20
0805	2012	1.00	1.35	1.55	4.40	2.60	0.90	1.15	1.45	3.50	2.00	0.75	0.95	1.35	2.80	1.70
1206	3216	1.60	1.65	1.90	5.90	2.90	1.50	1.45	1.80	5.00	2.30	1.40	1.25	1.70	4.30	2.00
1210	3225	1.60	1.65	2.80	5.90	3.80	1.50	1.45	2.70	5.00	3.20	1.40	1.25	2.60	4.30	2.90

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805 and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

**Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC–7351).

Image below based on Density Level B for an EIA 1210 case size.



## Soldering Process

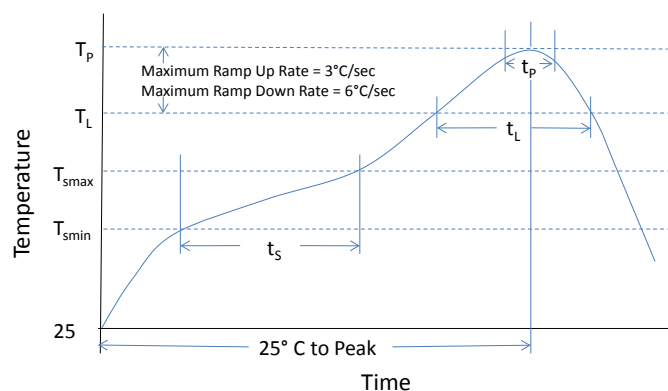
### Recommended Soldering Technique:

- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- All other EIA case sizes are limited to solder reflow only

### Recommended Reflow Soldering Profile:

KEMET's families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Termination Finish	
	SnPb	100% Matte Sn
<b>Preheat/Soak</b>		
Temperature Minimum ( $T_{Smin}$ )	100°C	150°C
Temperature Maximum ( $T_{Smax}$ )	150°C	200°C
Time ( $t_s$ ) from $T_{Smin}$ to $T_{Smax}$	60 – 120 seconds	60 – 120 seconds
Ramp-Up Rate ( $T_L$ to $T_P$ )	3°C/second maximum	3°C/second maximum
Liquidous Temperature ( $T_L$ )	183°C	217°C
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds
Peak Temperature ( $T_P$ )	235°C	260°C
Time Within 5°C of Maximum Peak Temperature ( $t_p$ )	20 seconds maximum	30 seconds maximum
Ramp-Down Rate ( $T_P$ to $T_L$ )	6°C/second maximum	6°C/second maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum



Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

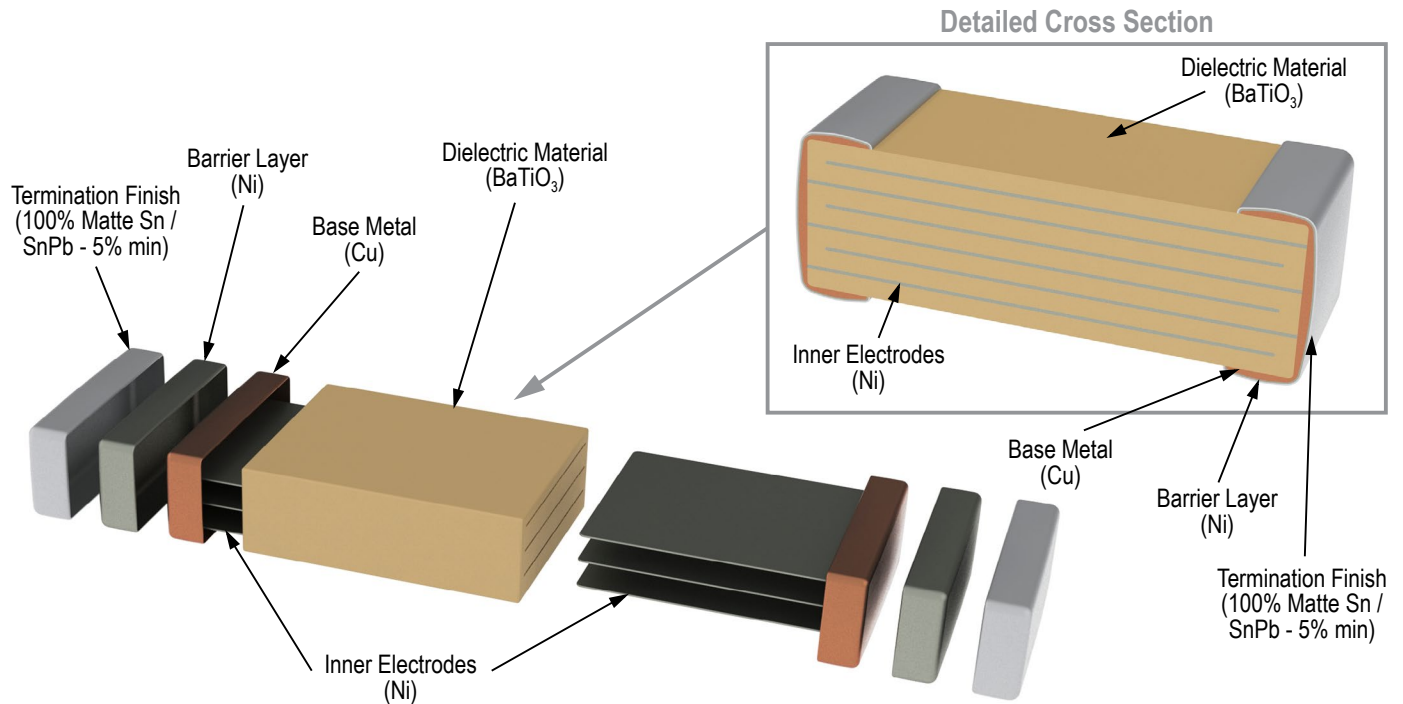
**Table 4 – Performance & Reliability: Test Methods and Conditions**

Stress	Reference	Test or Inspection Method
Terminal Strength	JIS-C-6429	Appendix 1, Note: Force of 1.8 kg for 60 seconds.
Board Flex	JIS-C-6429	Appendix 2, Note: Standard termination system – 2.0 mm (minimum) for all except 3 mm for C0G. Flexible termination system – 3.0 mm (minimum).
Solderability	J-STD-002	Magnification 50 X. Conditions:
		a) Method B, 4 hours @ 155°C, dry heat @ 235°C
		b) Method B @ 215°C category 3
		c) Method D, category 3 @ 260°C
Temperature Cycling	JESD22 Method JA-104	1,000 cycles (-55°C to +150°C). Measurement at 24 hours +/- 2 hours after test conclusion.
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85%RH and rated voltage. Add 100K ohm resistor. Measurement at 24 hours +/- 2 hours after test conclusion.
		Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V. Add 100 K ohm resistor. Measurement at 24 hours +/- 2 hours after test conclusion.
Moisture Resistance	MIL-STD-202 Method 106	t = 24 hours/cycle. Steps 7a and 7b not required. Unpowered. Measurement at 24 hours. +/- 2 hours after test conclusion.
Thermal Shock	MIL-STD-202 Method 107	-55°C/+150. Note: Number of cycles required – 300. Maximum transfer time – 20 seconds. Dwell time – 15 minutes. Air – Air.
High Temperature Life	MIL-STD-202 Method 108 /EIA-198	1,000 hours at 150°C with 2 X rated voltage applied.
Storage Life	MIL-STD-202 Method 108	150°C, 0 VDC for 1,000 hours.
Vibration	MIL-STD-202 Method 204	5 g's for 20 min., 12 cycles each of 3 orientations. Note: Use 8" X 5" PCB 0.031" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213, Condition F.
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical, OKEM Clean or equivalent.

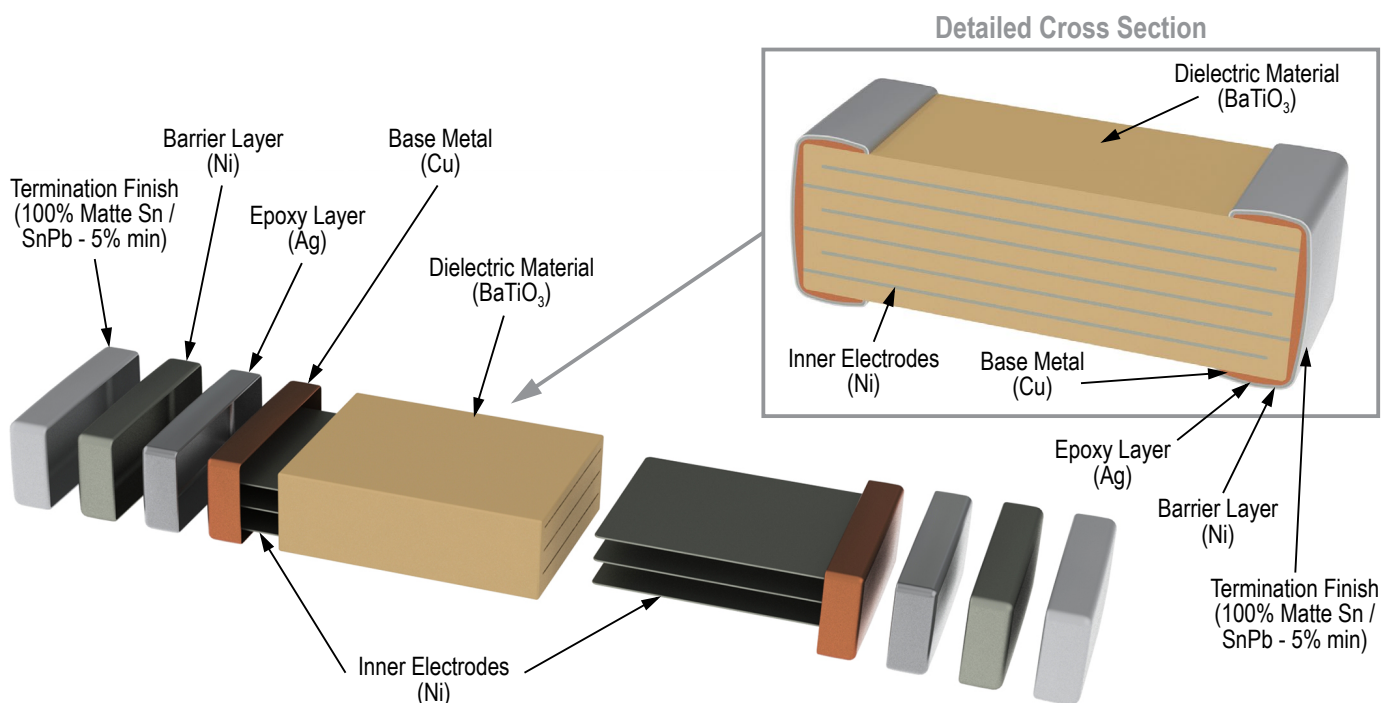
## Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature– reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.

## Construction – Standard Termination



## Construction – Flexible Termination



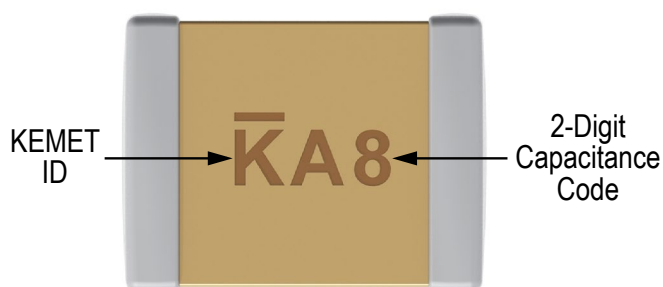
## Capacitor Marking (Optional):

These surface mount multilayer ceramic capacitors are normally supplied unmarked. If required, they can be marked as an extra cost option. Marking is available on most KEMET devices but must be requested using the correct ordering code identifier(s). If this option is requested, two sides of the ceramic body will be laser marked with a “K” to identify KEMET, followed by two characters (per EIA-198 - see table below) to identify the capacitance value. EIA 0603 case size devices are limited to the “K” character only.

Laser marking option is not available on:

- C0G, Ultra Stable X8R and Y5V dielectric devices
- EIA 0402 case size devices
- EIA 0603 case size devices with Flexible Termination option.
- KPS Commercial and Automotive Grade stacked devices.
- X7R dielectric products in capacitance values outlined below

Marking appears in legible contrast. Illustrated below is an example of an MLCC with laser marking of “KA8”, which designates a KEMET device with rated capacitance of 100  $\mu$ F. Orientation of marking is vendor optional.



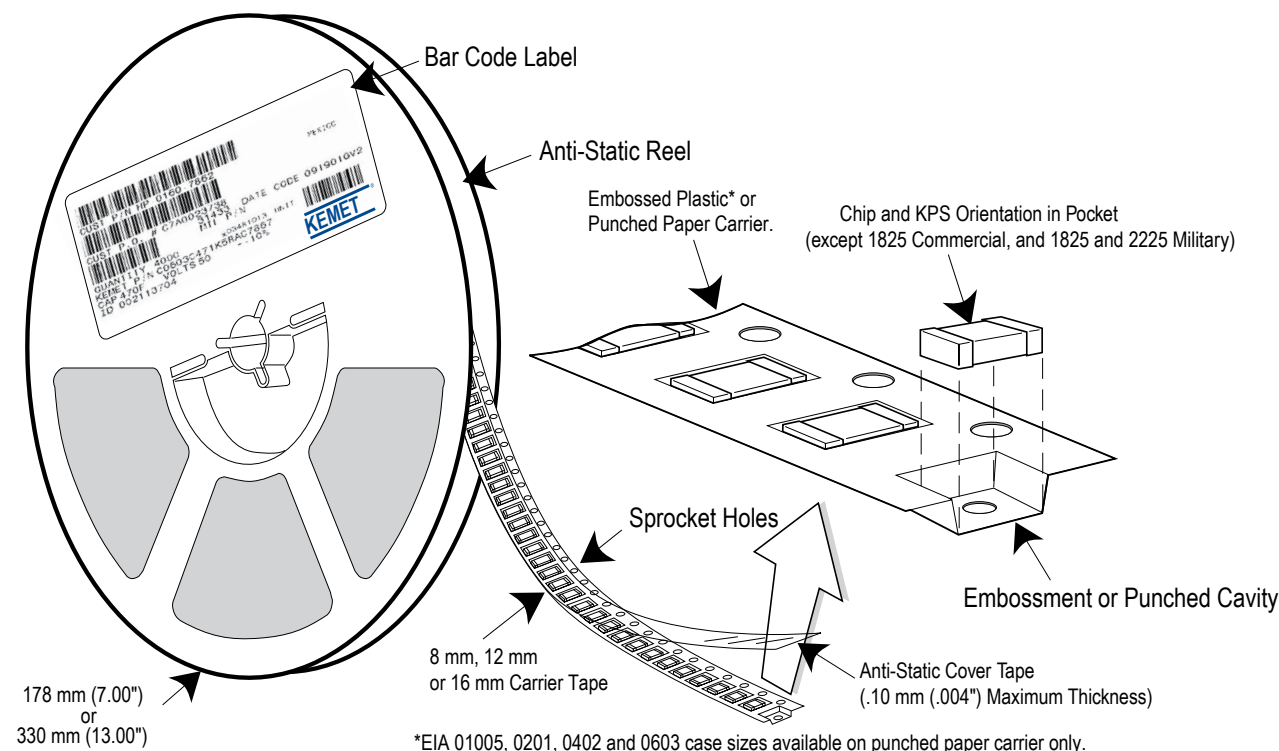
EIA Case Size	Metric Size Code	Capacitance
0603	1608	$\leq 170$ pF
0805	2012	$\leq 150$ pF
1206	3216	$\leq 910$ pF
1210	3225	$\leq 2,000$ pF
1808	4520	$\leq 3,900$ pF
1812	4532	$\leq 6,700$ pF
1825	4564	$\leq 0.018$ $\mu$ F
2220	5650	$\leq 0.027$ $\mu$ F
2225	5664	$\leq 0.033$ $\mu$ F

## Capacitor Marking (Optional) cont'd

Capacitance (pF) For Various Alpha/Numeral Identifiers										
Alpha Character	Numeral									
	9	0	1	2	3	4	5	6	7	8
	Capacitance (pF)									
A	0.1	10	10	100	1,000	10,000	100,000	1,000,000	10,000,000	100,000,000
B	0.11	1.1	11	110	1,100	11,000	110,000	1,100,000	11,000,000	110,000,000
C	0.12	12	12	120	1,200	12,000	120,000	1,200,000	12,000,000	120,000,000
D	0.13	13	13	130	1,300	13,000	130,000	1,300,000	13,000,000	130,000,000
E	0.15	15	15	150	1,500	15,000	150,000	1,500,000	15,000,000	150,000,000
F	0.16	16	16	160	1,600	16,000	160,000	1,600,000	16,000,000	160,000,000
G	0.18	18	18	180	1,800	18,000	180,000	1,800,000	18,000,000	180,000,000
H	0.2	20	20	200	2,000	20,000	200,000	2,000,000	20,000,000	200,000,000
J	0.22	22	22	220	2,200	22,000	220,000	2,200,000	22,000,000	220,000,000
K	0.24	24	24	240	2,400	24,000	240,000	2,400,000	24,000,000	240,000,000
L	0.27	27	27	270	2,700	27,000	270,000	2,700,000	27,000,000	270,000,000
M	0.3	30	30	300	3,000	30,000	300,000	3,000,000	30,000,000	300,000,000
N	0.33	33	33	330	3,300	33,000	330,000	3,300,000	33,000,000	330,000,000
P	0.36	36	36	360	3,600	36,000	360,000	3,600,000	36,000,000	360,000,000
Q	0.39	39	39	390	3,900	39,000	390,000	3,900,000	39,000,000	390,000,000
R	0.43	43	43	430	4,300	43,000	430,000	4,300,000	43,000,000	430,000,000
S	0.47	47	47	470	4,700	47,000	470,000	4,700,000	47,000,000	470,000,000
T	0.51	51	51	510	5,100	51,000	510,000	5,100,000	51,000,000	510,000,000
U	0.56	56	56	560	5,600	56,000	560,000	5,600,000	56,000,000	560,000,000
V	0.62	62	62	620	6,200	62,000	620,000	6,200,000	62,000,000	620,000,000
W	0.68	68	68	680	6,800	68,000	680,000	6,800,000	68,000,000	680,000,000
X	0.75	75	75	750	7,500	75,000	750,000	7,500,000	75,000,000	750,000,000
Y	0.82	82	82	820	8,200	82,000	820,000	8,200,000	82,000,000	820,000,000
Z	0.91	91	91	910	9,100	91,000	910,000	9,100,000	91,000,000	910,000,000
a	0.25	25	25	250	2,500	25,000	250,000	2,500,000	25,000,000	250,000,000
b	0.35	35	35	350	3,500	35,000	350,000	3,500,000	35,000,000	350,000,000
d	0.4	40	40	400	4,000	40,000	400,000	4,000,000	40,000,000	400,000,000
e	0.45	45	45	450	4,500	45,000	450,000	4,500,000	45,000,000	450,000,000
f	0.5	50	50	500	5,000	50,000	500,000	5,000,000	50,000,000	500,000,000
m	0.6	60	60	600	6,000	60,000	600,000	6,000,000	60,000,000	600,000,000
n	0.7	70	70	700	7,000	70,000	700,000	7,000,000	70,000,000	700,000,000
t	0.8	80	80	800	8,000	80,000	800,000	8,000,000	80,000,000	800,000,000
y	0.9	90	90	900	9,000	90,000	900,000	9,000,000	90,000,000	900,000,000

## Tape & Reel Packaging Information

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.



**Table 5 – Carrier Tape Configuration, Embossed Plastic & Punched Paper (mm)**

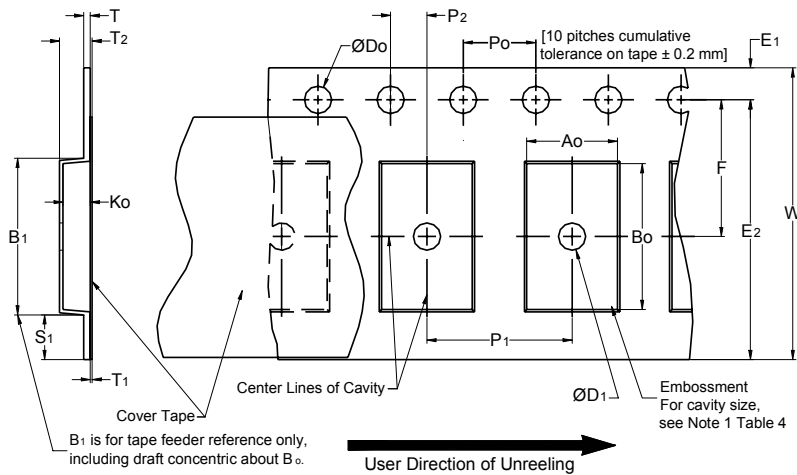
EIA Case Size	Tape size (W)*	Embossed Plastic		Punched Paper	
		7" Reel	13" Reel	7" Reel	13" Reel
		Pitch (P <sub>1</sub> )*		Pitch (P <sub>1</sub> )*	
01005 – 0402	8			2	2
0603	8			4	4
0805	8	4	4	4	4
1206 – 1210	8	4	4	4	4
1805 – 1808	12	4	4		
≥ 1812	12	8	8		
KPS 1210	12	8	8		
KPS 1812 & 2220	16	12	12		
Array 0508 & 0612	8	4	4		

\*Refer to Figures 1 & 2 for W and P<sub>1</sub> carrier tape reference locations.

\*Refer to Tables 6 & 7 for tolerance specifications.



**Figure 1 – Embossed (Plastic) Carrier Tape Dimensions**



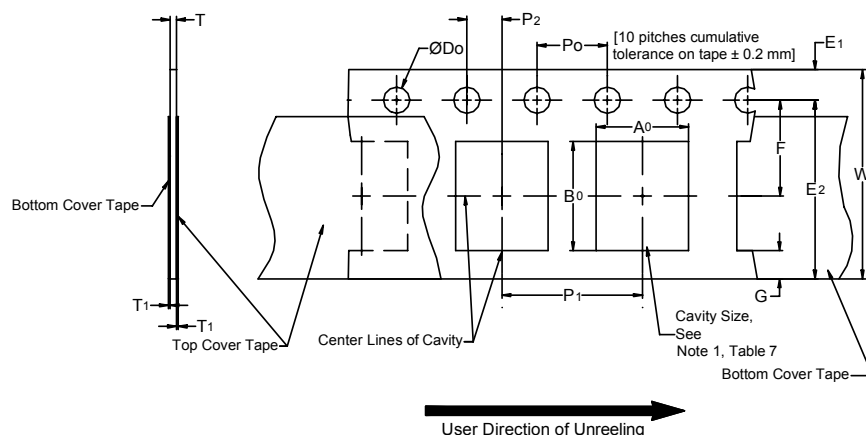
**Table 6 – Embossed (Plastic) Carrier Tape Dimensions**

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.0 (0.039)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	25.0 (0.984)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
12 mm		1.5 (0.059)				30 (1.181)			
16 mm									
Variable Dimensions — Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)	Note 5	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)		
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5 ±0.05 (0.138 ±0.002)	12.0 ±0.10 (0.157 ±0.004)	4.6 (0.181)	16.3 (0.642)		

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
2. The tape with or without components shall pass around R without damage (see Figure 6).
3. If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481 paragraph 4.3 section b).
4. B<sub>1</sub> dimension is a reference dimension for tape feeder clearance only.
5. The cavity defined by A<sub>0</sub>, B<sub>0</sub> and K<sub>0</sub> shall surround the component with sufficient clearance that:
  - (a) the component does not protrude above the top surface of the carrier tape.
  - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3).
  - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4).
  - (e) for KPS Series product, A<sub>0</sub> and B<sub>0</sub> are measured on a plane 0.3 mm above the bottom of the pocket.
  - (f) see Addendum in EIA Standard 481 for standards relating to more precise taping requirements.

**Figure 2 – Punched (Paper) Carrier Tape Dimensions**



**Table 7 – Punched (Paper) Carrier Tape Dimensions**

Metric will govern

Constant Dimensions — Millimeters (Inches)							
Tape Size	$D_0$	$E_1$	$P_0$	$P_2$	$T_1$ Maximum	G Minimum	R Reference Note 2
8 mm	$1.5 +0.10 -0.0$ (0.059 +0.004 -0.0)	$1.75 \pm 0.10$ (0.069 ±0.004)	$4.0 \pm 0.10$ (0.157 ±0.004)	$2.0 \pm 0.05$ (0.079 ±0.002)	0.10 (0.004) Maximum	0.75 (0.030)	25 (0.984)
Variable Dimensions — Millimeters (Inches)							
Tape Size	Pitch	$E_2$ Minimum	F	$P_1$	T Maximum	W Maximum	$A_0 B_0$
8 mm	Half (2 mm)	6.25 (0.246)	$3.5 \pm 0.05$ (0.138 ±0.002)	$2.0 \pm 0.05$ (0.079 ±0.002)	1.1 (0.098)	8.3 (0.327)	Note 1
8 mm	Single (4 mm)			$4.0 \pm 0.10$ (0.157 ±0.004)		8.3 (0.327)	

- The cavity defined by  $A_0$ ,  $B_0$  and  $T$  shall surround the component with sufficient clearance that:
  - the component does not protrude beyond either surface of the carrier tape.
  - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - rotation of the component is limited to 20° maximum (see Figure 3).
  - lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4).
  - see Addendum in EIA Standard 481 for standards relating to more precise taping requirements.
- The tape with or without components shall pass around R without damage (see Figure 6).

## Packaging Information Performance Notes

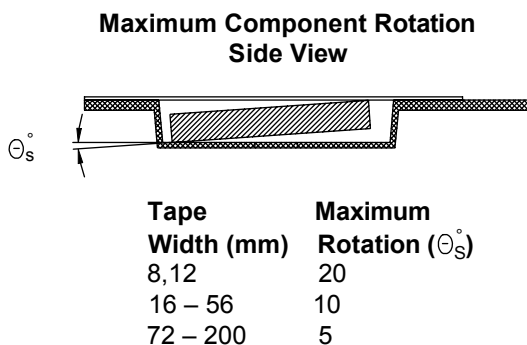
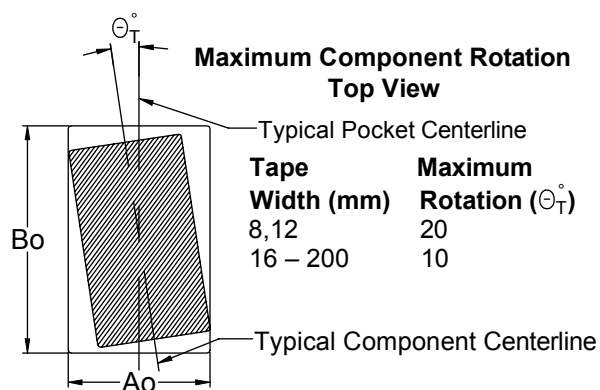
- Cover Tape Break Force:** 1.0 Kg minimum.
- Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

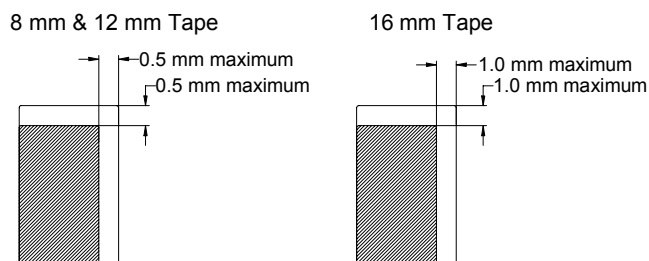
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

- Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

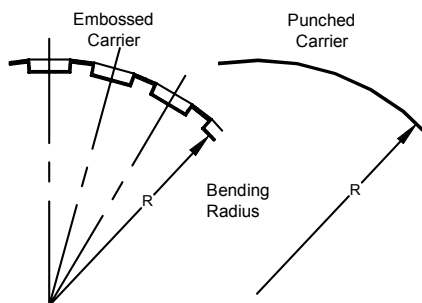
## Figure 3 – Maximum Component Rotation



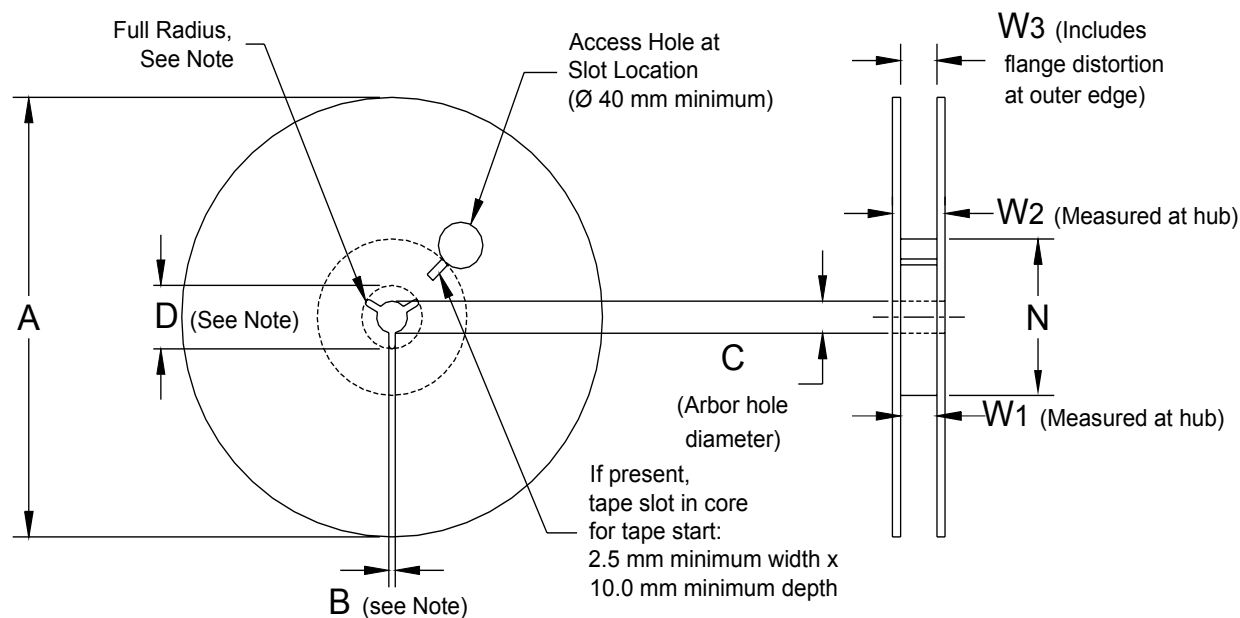
## Figure 4 – Maximum Lateral Movement



## Figure 5 – Bending Radius



**Figure 6 – Reel Dimensions**



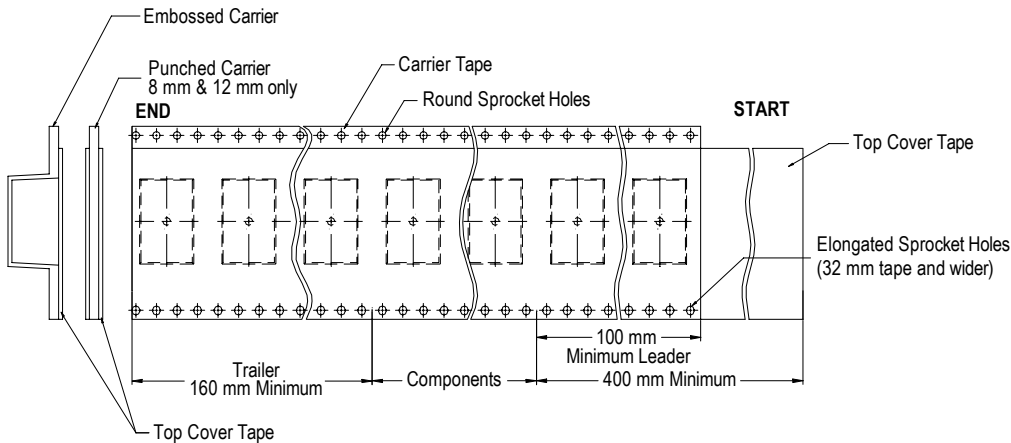
Note: Drive spokes optional; if used, dimensions B and D shall apply.

**Table 8 – Reel Dimensions**

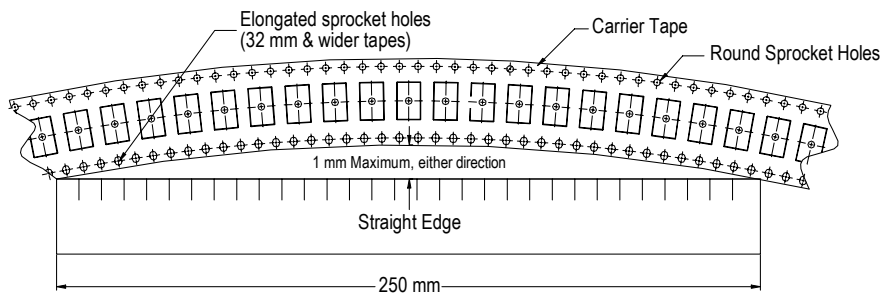
Metric will govern

Constant Dimensions — Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
8 mm	178 ±0.20 (7.008 ±0.008) or 330 ±0.20 (13.000 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)
12 mm				
16 mm				
Variable Dimensions — Millimeters (Inches)				
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>
8 mm	50 (1.969)	8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)	Shall accommodate tape width without interference
12 mm		12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	

**Figure 7 – Tape Leader & Trailer Dimensions**



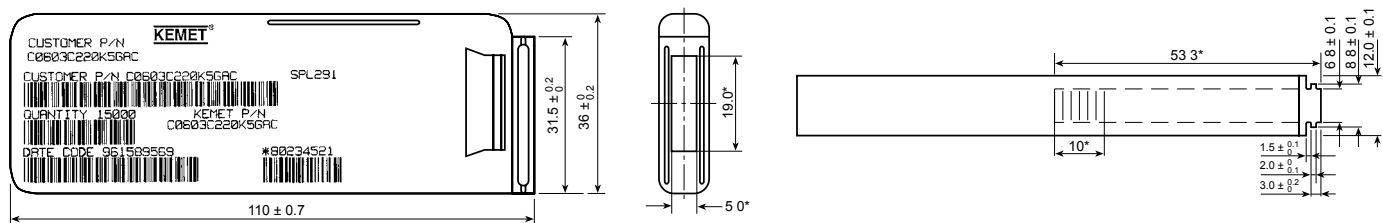
**Figure 8 – Maximum Camber**



**Figure 9 – Bulk Cassette Packaging (Ceramic Chips Only)**

Meets Dimensional Requirements IEC-286 and EIAJ 7201

Unit mm \*Reference



**Table 9 – Capacitor Dimensions for Bulk Cassette**

Cassette Packaging – Millimeters

EIA Size Code	Metric Size Code	L Length	W Width	B Bandwidth	S Separation Minimum	T Thickness	Number of Pieces/Cassette
0402	1005	1.0 ±0.05	0.5 ±0.05	0.2 to 0.4	0.3	0.5 ±0.05	50,000
0603	1608	1.6 ±0.07	0.8 ±0.07	0.2 to 0.5	0.7	0.8 ±0.07	15,000

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